

General Description

The Sanrise SRC60R090FBS is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R090FBS break down voltage is 600V and it has a high rugged avalanche characteristics.

The SRC60R090FBS is available in TO-263-2, TO-220F, TO-220C and TO-247 packages.

Features

- Ultra Low $R_{DS(ON)} = 90m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 55nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Optimized switching process
- Non-automotive Qualified
- Ultra-fast body diode

Application

- High Performance PS

Symbol

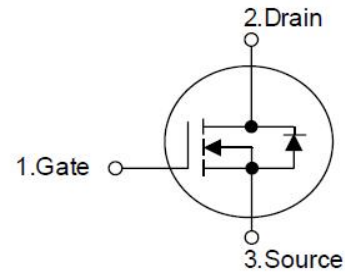


Figure 1 Symbol of SRC60R090FBS

Package Type

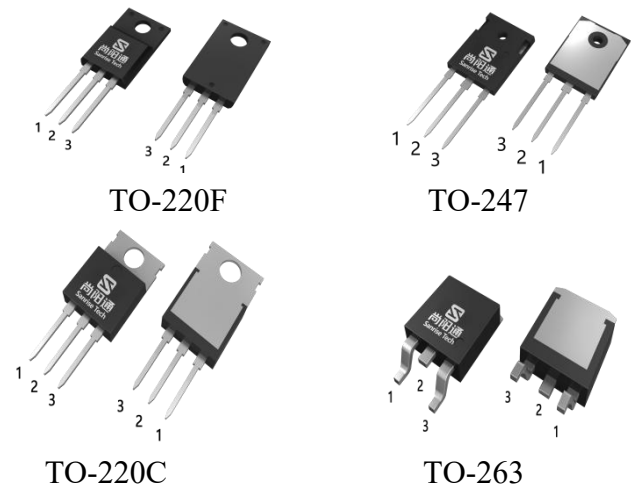
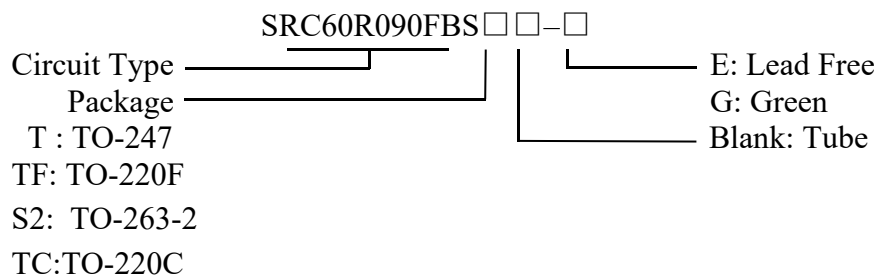


Figure 2 Package Types of SRC60R090FBS

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-247	SRC60R090FBSTG-G	SRC60R090FBSTG	Tube
TO-220F	SRC60R090FBSTFG-G	SRC60R090FBSTFG	Tube
TO-220C	SRC60R090FBSTCG-G	SRC60R090FBSTCG	Tube
TO-263-2	SRC60R090FBSS2TR-G	SRC60R090FBSS2G	Tape & Reel

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DSS}	600	V
Gate-Source Voltage (static)		V _{GSS}	±20	V
Gate-Source Voltage (dynamic), AC (f>1 Hz)		V _{GSS}	±30	V
Power Dissipation (T _c =25°C, TO-220F)		P _{tot}	32	W
Power Dissipation (T _c =25°C, TO-247, TO-220C, TO-263-2)		P _{tot}	255	W
Continuous Drain Current	T _c =25°C	I _D	37	A
	T _c =100°C		23	
	T _c =125°C		16	
Pulsed Drain Current (Note 2)		I _{DM}	111	A
Avalanche Energy, Single Pulse (Note 3)		E _{AS}	160	mJ
Avalanche Energy, Repetitive (Note 2)		E _{AR}	0.2	mJ
Avalanche Current, Repetitive (Note 2)		I _{AR}	2.2	A
Continuous Diode Forward Current		I _S	37	A
Diode Pulse Current		I _{S,PULSE}	111	A
MOSFET dv/dt Ruggedness, V _{DS} ≤480V		dv/dt	80	V/ns
Reverse Diode dv/dt, V _{DS} ≤480V, I _{SD} ≤I _D		dv/dt	50	V/ns
Operating Junction Temperature		T _J	150	°C
Storage Temperature		T _{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		T _{LEAD}	260	°C

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- I_{AS}=2.2A, V_{DD}=60V, R_G=25Ω, Starting T_J=25°C

Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	R _{thJC}			3.9	°C /W
	TO-247				0.49	
	TO-220C				0.49	
	TO-263-2				0.49	
Thermal resistance, Junction-to-Ambient	TO-220F	R _{thJA}			78	°C /W
	TO-247				60	
	TO-220C				60	
	TO-263-2				60	

Electrical Characteristics

$T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			20	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	4.0	5.0	6.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		70	90	mΩ
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		2.2		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=400V, V_{GS}=0V,$		2.3		nF
Output Capacitance	C_{OSS}	$f=100kHz$		68		pF
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V,$ $V_{DS}=0\dots 480V$		98		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			600		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=20A$ $R_G=3.3\Omega, V_{GS}=10V$		25		ns
Rise Time	t_r			6		
Turn-off Delay Time	$t_{d(off)}$			80		
Fall Time	t_f			5		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=20A$ $V_{GS}=0 \text{ to } 10V$		15.6		nC
Gate to Drain Charge	Q_{gd}			25		
Gate Charge Total	Q_g			55		
Gate Plateau Voltage	$V_{plateau}$				6.5	V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=20A$		0.9	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=20A$ $dI_F/dt=100A/\mu s$		149		ns
Reverse Recovery Charge	Q_{rr}				1.2	μC
Peak Reverse Recovery Current	I_{rrm}				15	A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480V



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